

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT6656BIS6-3.3#TRPBF

(Engineering Calculation)

TSOT-23

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TOTAL MASS (g):

0.01254276

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000567	1000000	45205.38		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0	0	0		
		Iron (Fe)	7439-89-6	0.002726	580000	217336.6		
		Phosporus (P)	7723-14-0	0	0	0		
		Zinc (Zn)	7440-66-6	0	0	0		
		Nickel (Ni)	7440-02-0	0.001974	420000	157381.7		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.0047	1000000	374718.3
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.000643756	1000000	51324.92		
		External Plating Total:				0.000643756	1000000	51324.92
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	8E-05	1000000	6378.183		
		Internal Plating Total:				8E-05	1000000	6378.183
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000409	750000	32608.46		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Resin (EP)		0.000136	250000	10842.91		
Die Attach Total:				0.000545	1000000	43451.38		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000772	130000	61549.47		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.00493	830000	393055.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0		
		Metal Hydroxid		0.000208	35000	16583.28		
		Carbon Black (C)	1333-86-4	3E-05	5000	2391.819		
		Encapsulation Total:				0.00594	1000000	473580.1
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	6.7E-05	1000000	5341.729		